

# φ0.050 Ultra Micro-Hole Drilling Performance

## φ0.050 ドリル 加工事例

用途: 半導体パッケージ、各種デバイス用基板 等 FBGA、BGA、Device substrate etc...

### Drilling Condition 加工条件

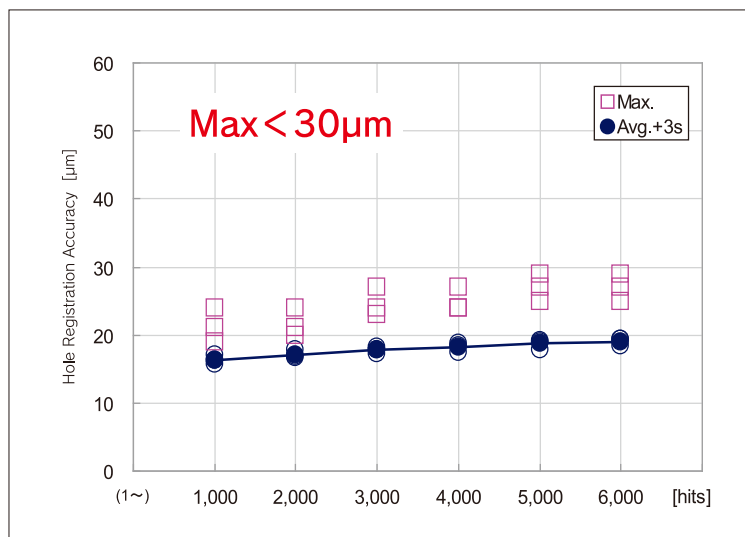
Work Material : BT CCL-HL832HS t0.1(Double Sided) x 3 stack height 3/3μmCopper

S : 350,000 min<sup>-1</sup> F : 1.75 m/min f : 5 μm/rev

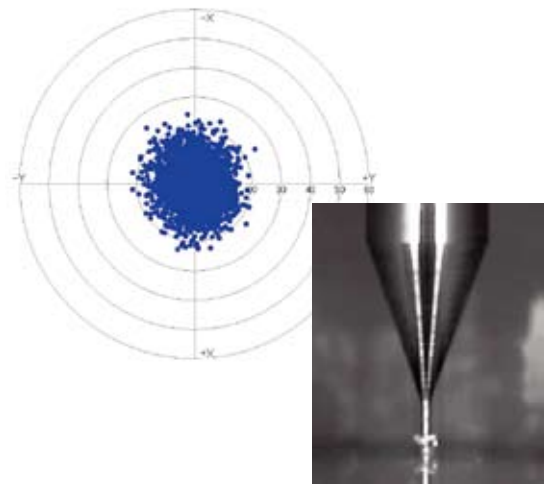
Set Life : 6,000 hits

High Quality & High Efficiency Drilling  
高品質 & 高効率加工を実現

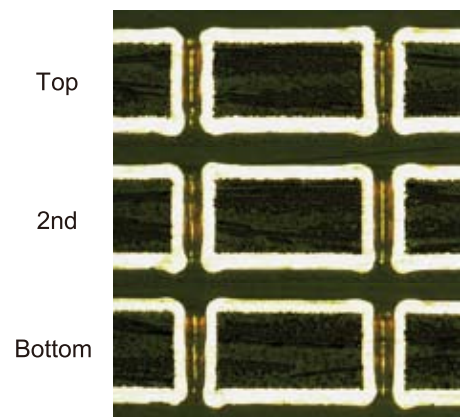
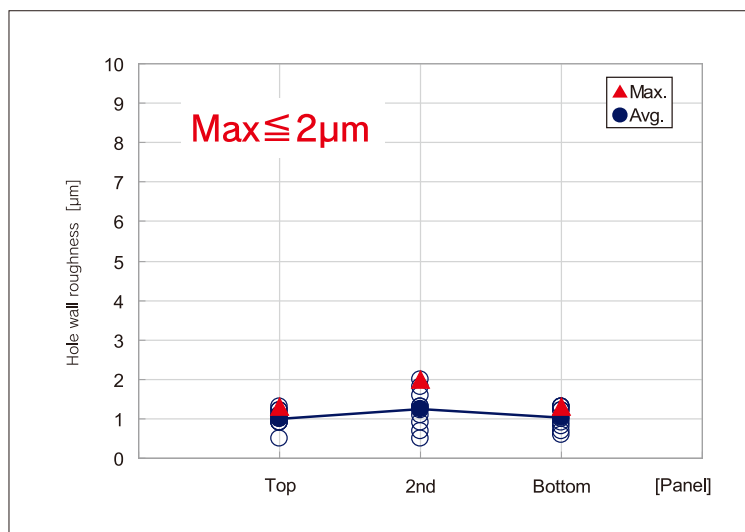
### Hole Registration Accuracy 穴位置精度



6,000 hits



### Hole Wall Quality at 6,000th hit 内壁粗さ



特許出願中